

IN THE CLAIMS:

Claims 1-20 have been amended herein. All of the pending claims 1 through 20 are presented below. This listing of claims will replace all prior versions and listings in the application. Please enter these claims as amended.

1. (Currently Amended) A method for designing a rerouting element for use with a semiconductor device including at least one bond pad positioned substantially centrally on a surface thereof, comprising:

configuring at least one contact location on a first surface of a substantially planar member, ~~said the~~ at least one contact location mirroring a position of the at least one bond pad on the surface of the semiconductor device;

configuring at least one conductive trace location extending from ~~said the~~ at least one contact location toward a periphery of ~~said the~~ substantially planar member; and

configuring at least one rerouted bond pad location proximate ~~said the~~ periphery, ~~said the~~ at least one rerouted bond pad location being configured to be exposed beyond a periphery of another semiconductor device upon positioning ~~said the~~ another semiconductor device over the surface of the semiconductor device.

2. (Currently Amended) The method of claim 1, wherein ~~said~~ configuring at least one contact location comprises configuring a plurality of contact locations, each contact location of ~~said the~~ plurality of contact locations mirroring a location of a corresponding bond pad on the surface of the semiconductor device.

3. (Currently Amended) The method of claim 2, wherein ~~said~~ configuring at least one conductive trace location comprises configuring a plurality of conductive trace locations, each conductive trace location of ~~said the~~ plurality of conductive trace locations extending from a corresponding contact location toward ~~said the~~ periphery of ~~said the~~ substantially planar member.

4. (Currently Amended) The method of claim 3, ~~wherein comprising configuring~~ each conductive trace location of ~~said the~~ plurality of conductive trace locations ~~extends to extend~~ toward a single edge of ~~said the~~ substantially planar member.

5. (Currently Amended) The method of claim 3, wherein ~~said~~ configuring at least one rerouted bond pad location comprises configuring a plurality of rerouted bond pad locations, each rerouted bond pad location of ~~said the~~ plurality of rerouted bond pad locations being continuous with an end of a corresponding conductive trace location and located proximate ~~said the periphery of~~ ~~said the~~ substantially planar member.

6. (Currently Amended) The method of claim 5, ~~wherein comprising configuring~~ each rerouted bond pad location of ~~said the~~ plurality of rerouted bond pad locations is configured to be exposed beyond a periphery of ~~said the~~ another semiconductor device upon positioning of ~~said the~~ another semiconductor device over the surface of the semiconductor device.

7. (Currently Amended) The method of claim 1, wherein ~~said~~ configuring ~~said the~~ at least one rerouted bond pad location comprises configuring ~~said the~~ at least one rerouted bond pad location to facilitate connection of a discrete conductive element thereto with ~~said the~~ another semiconductor device positioned over the surface of the semiconductor device.

8. (Currently Amended) A method for assembling semiconductor devices in a stacked arrangement, comprising:
providing a semiconductor device with at least one bond pad positioned substantially centrally on a surface thereof; and
positioning a rerouting element over ~~said the~~ surface of ~~said the~~ semiconductor device with a contact of ~~said the~~ rerouting element communicating with ~~said the~~ at least one bond pad, a circuit trace of ~~said the~~ rerouting element extending laterally toward a periphery of ~~said the~~ semiconductor device and establishing communication between ~~said the~~ at least one

bond pad and at least one rerouted bond pad located proximate a periphery of said the semiconductor device at a location where said the at least one rerouted bond pad will remain exposed upon positioning another semiconductor device over said the surface of the semiconductor device.

9. (Currently Amended) The method of claim 8, wherein said providing said the semiconductor device comprises providing a semiconductor device with a plurality of bond pads, at least some of which are positioned at substantially central locations on said the surface.

10. (Currently Amended) The method of claim 9, wherein said positioning said the rerouting element comprises positioning a rerouting element comprising:
a plurality of contacts, each contact of said the plurality of contacts being positioned correspondingly to a position of a corresponding bond pad of said the semiconductor device;
a plurality of conductive traces, each conductive trace of said the plurality of conductive traces extending laterally from a corresponding contact of said the plurality of contacts toward said the periphery of said the semiconductor device; and
a plurality of rerouted bond pads, each rerouted bond pad of said the plurality of rerouted bond pads being positioned at an end of a corresponding conductive trace, proximate said the periphery of said the semiconductor device.

11. (Currently Amended) The method of claim 10, wherein said positioning said the rerouting element comprises positioning a rerouting element with each rerouted bond pad of said the plurality of rerouted bond pads being positioned proximate a single peripheral edge of said the semiconductor device.

12. (Currently Amended) The method of claim 10, wherein said positioning said the rerouting element comprises positioning a rerouting element with each rerouted bond pad of said

the plurality of rerouted bond pads being positioned to be exposed beyond a periphery of the
another semiconductor device upon being positioned over-said the surface of-said the
semiconductor device.

13. (Currently Amended) The method of claim 8, further comprising:
positioning the another semiconductor device over-said the rerouting element,-said the at least
one rerouted bond pad of-said the rerouting element being exposed beyond a periphery of
said the another semiconductor device.

14. (Currently Amended) The method of claim 13, further comprising:
securing-said the semiconductor device to a carrier substrate.

15. (Currently Amended) The method of claim 14, wherein said-securing comprises
securing-said the semiconductor device to at least one of a circuit board, an interposer, an
additional semiconductor device, and leads.

16. (Currently Amended) The method of claim 14, further comprising:
positioning at least one discrete conductive element between-said the at least one rerouted bond
pad and a corresponding contact area of-said the carrier substrate.

17. (Currently Amended) The method of claim 16, wherein said-positioning
comprises at least one of wire bonding, tape-automated bonding, and thermocompression
bonding.

18. (Currently Amended) The method of claim 14, further comprising:
encapsulating at least portions of-said the semiconductor device,-said the another semiconductor
device, and regions of-said the carrier substrate adjacent to-said the semiconductor device.

19. (Currently Amended) The method of claim 18, wherein ~~said~~ encapsulating comprises glob top encapsulating.

20. (Currently Amended) The method of claim 18, wherein ~~said~~ encapsulating comprises one of transfer molding and pot molding.